ABSTRACT

STRIP-FABRICATED FLIP CHIP IN PACKAGE AND FLIP CHIP-SYSTEM IN PACKAGE HEAT SPREADER ASSEMBLIES AND FABRICATION METHODS THEREFOR

A method for fabricating a semiconductor package with a substrate in a strip format is provided. Semiconductor devices are attached in a strip format to the substrate, and a thermal interface material is applied to the semiconductor devices. A flat panel heat spreader is attached to each semiconductor device. The semiconductor devices are encapsulated with open encapsulation, leaving the surface of the flat panel heat spreader opposite the substrate externally exposed. Individual semiconductor packages are then singulated from the strip format. (Fig. 5)